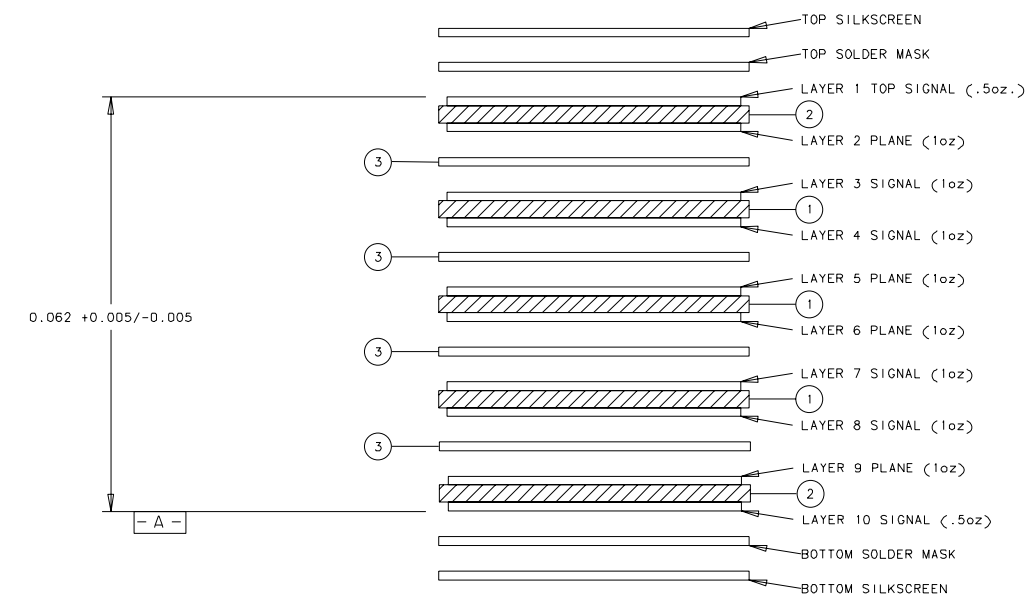
REVISIONS														
LTR	ZONE	DESCRIPTION		DWN	CHK	STRUCT	MATL	Thermal CONT			ENGR	DSGN SUPV	DATA MGT	RELEASE DATE
A		INITIAL RELEASE	CODE D	SEE TITLE BLOCK										



DETAIL A
NO SCALE

TOP AND BOTTOM LAYERS .008 TRACES/.007 SPACES MINIMUM
INTERNAL SIGNAL LAYERS .008 TRACES/.007 SPACES MINIMUM

13. SIGNAL TRACE WIDTH SHALL BE .0075 MINIMUM.
12. MAXIMUM BOW AND TWIST SHALL NOT EXCEED 1%.
11. ONE SET OF COUPONS SHALL BE PROCESSED ALONG WITH THE BOARD THROUGH FUSING FOR SUBMITTAL WITH THE BOARD.
10. FILL ALL VIAS PER SECTION 3.6 (OPTIONAL).
9. INK STAMP REVISION LETTER AND SERIAL NUMBER USING ITEM 6 PER SECTION 3.3. CHARACTER HEIGHT TO BE .09 INCHES (APPROX.)
8. CONTINUITY AND SHORTS TESTING SHALL BE PERFORMED ON EACH PWB,AND THE DOCUMENTATION DELIVERED WITH THE FINISHED PWB. SHORTS TESTING SHALL BE AT A MINIMUM OF 200 VOLTS D.C.
7. AFTER APPLICATION OF SOLDER MASK OVER BARE COPPER (SMOBC) COAT WITH SOLDER, USING HOT AIR LEVELING (HASL) PROCESS. SOLDER THICKNESS AT THE CREST TO BE .0003 TO .001 INCH. THERE SHALL BE NO SOLDER UNDERNEATH SOLDER MASK.
6. APPLY SOLDER MASK,ITEM 5, TO TOP AND BOTTOM OVER BARE COPPER PER SECTION 3.6, COMPONENT PADS TO BE FREE FROM BLEEDING OR MISREGISTRATION.
5. COPPER PLATING IN HOLES SHALL BE .001 INCHES MINIMUM THICKNESS. .0015 INCHES MINIMUM AVERAGE THICKNESS.
4. FABRICATE PRINTED WIRING BOARD PER SECTION 3.6.
3. SEPARATION BETWEEN ADJACENT CONDUCTOR LAYERS TO BE .0035 INCHES MINIMUM AND CONSIST OF A MINIMUM OF 2 PLIES.
2. THIS DOCUMENT AND RELATED ARTWORK ARE COMPUTER GENERATED. CHANGES ARE TO BE PERFORMED ON ORIGINAL DATABASE ON FILE IN SECTION 349.
1. ALL SECTIONS AND SUBSECTIONS REFERRED TO IN THESE NOTES ARE CONTAINED IN JPL SPECIFICATION DOCUMENT D-8208.

NOTES: UNLESS OTHERWISE SPECIFIED

QTY REQD	FSCM NO.	PART OR IDENTIFYING NO.	NOMENCLATURE OR DESCRIPTION	MATERIAL SPECIFICATION	ZONE	ITEM NO.
						16
						15
						14
						13
						12
						11
						10
						9
						8
						7
						6
AR	5	HYSOL M-9-N WORNOWINK	INK, PERMANENT MARKING, POLYCLAD/ETHONE	BS502673		5
AR	4	PROBIMER 52	SOLDERMASK, PHOTO IMAGABLE	IPC-SM-840 CLASS 3		4
5	3	PC-G1	GLASS BASE POLYIMIDE RESIN PREPREG, B-STAGE	IPC-4101/40 PREPREG POLYIMIDE LAMINATE		3
2	2	G1N-XX-XC1/CH B2B	GLASS BASE POLYIMIDE RESIN CU CLAD .5D OZ./1 OZ.	IPC-4101/40		2
4	1	G1N-XX-XC1/C1 B2B	GLASS BASE POLYIMIDE RESIN CU CLAD 1 OZ./1 OZ.	IPC-4101/40		1

PARTS LIST

10229072	LAMP
NEXT ASSEMBLY	USED ON
APPLICATION	

UNLESS OTHERWISE SPECIFIED
DIMENSIONS ARE IN INCHES AND [MILLIMETERS]
TOLERANCES
DECIMALS .XX ± .01 .XXX ± .005
ANGLES ± 1/2°
DO NOT SCALE DRAWING
INTERPRET DWG PER ASME Y14.100M
MATERIAL

CONTRACT NO

APPVD		DATE
DWN	S. Wanger	10/01/03
CHK		
STRUCT		
MATL		
Thermal CONT		
PKG		
COGE		
ENGR		
DSGN SUPV		

JET PROPULSION LABORATORY
CALIFORNIA INSTITUTE OF TECHNOLOGY
PASADENA, CA 91109
RELEASED THROUGH SECTION EDMC

PRINTED CIRCUIT BOARD,
ROCKY-7 BOARD

SIZE	CAGE NO		REV
D	23835	10237371	A
SCALE NONE		UNCLASSIFIED	SHEET 1 OF 2

REV 4/00

MENTOR GRAPHICS GENERATED

10237371 REV A SHT 1 OF 2 DATE 10-01-03

10237371 REV A SHT 2 OF 2 DATE 10-01-03